

Please amend the subject application as follows:

IN THE CLAIMS:

- A
- ✓ 1. (Original) A method for testing an integrated circuit, comprising:
- providing a wafer having multiple die that are separated by a singulation area;
 - providing a visual functional indicator for each of some or all of the multiple die;
 - providing test circuitry for each of the some or all of the multiple die that have a visual functional indicator;
 - powering up the wafer to electrically activate the multiple die and initiate operation of the test circuitry;
 - performing predetermined tests with the test circuitry for the some or all of the multiple die;
 - outputting a test result to the visual functional indicator for the some or all of the multiple die; and
 - using the test result to create a visual indication on the wafer with each visual functional indicator corresponding to the test result.
- ✓ 2. (Original) The method of claim 1 further comprising:
- physically locating the visual functional indicator within each of some or all of the multiple die.
3. (Original) The method of claim 1 further comprising:
- physically locating the visual functional indicator external to the some or all of the multiple die and within a scribe area of the wafer.
- ✓ 4. (Original) The method of claim 1 further comprising:
- implementing the visual functional indicator as a light emitting diode (LED).
- ✓ 5. (Original) The method of claim 1 further comprising:
- repeating the predetermined tests to test the some or all of the multiple die under a plurality of differing operating conditions to determine whether the some

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or all of the multiple die are functional within a range of operating conditions.

- ✓ 6. (Original) The method of claim 1 further comprising:
providing multiple visual indicators on each of the some or all of the die, each of
the multiple visual indicators indicating functional operation of a separate
predetermined portion of a predetermined one of the some or all of the
multiple die.

- A' cont'd
7. (Original) The method of claim 1 further comprising:
implementing the visual functional indicator as a binary coded decimal (BCD)
light emitting diode (LED) that asserts a predetermined decimal upon
passing a corresponding predetermined functional test.

- ✓ 8. (Original) The method of claim 1 further comprising:
singulating the multiple die and segregating functional die of the multiple die
from non-functional die of the multiple die based upon the visual
indication.

9. (Original) The method of claim 1 further comprising:
recording the visual indication with either a camera or a high resolution imager to
form a data base that is used by a singulation tool to singulate the multiple
die and segregate the multiple die based on the visual indication.

Cancel claims 10-19.

- ✓ 20. (Newly Presented) A method for testing an integrated circuit, comprising:
providing a wafer having multiple die that are separated by a singulation area;
providing a visual functional indicator for each of the multiple die thereby
providing a plurality of visual indicators;
providing test circuitry for each of the multiple die;

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powering up the wafer to electrically activate the multiple die and initiate operation of the test circuitry;
performing predetermined tests with the test circuitry for each of the multiple die;
outputting a test result to the visual functional indicator for each of the multiple die; and
using the test result to create a visual indication on the wafer with each visual functional indicator corresponding to the test result.

- A
contd
21. (Newly Presented) The method of claim 20 further comprising:
using a portion of the plurality of visual indicators for both a test mode of operation and a normal functional mode of operation.
 22. (Newly Presented) The method of claim 20 further comprising:
positioning each respective visual functional indicator within a corresponding respective one of the multiple die.
 23. (Newly Presented) The method of claim 20 further comprising:
implementing each visual functional indicator with a light emitting diode (LED).
 24. (Newly Presented) A method for testing an integrated circuit, comprising:
providing a wafer having multiple die;
providing a visual functional indicator for each of the multiple die;
providing test circuitry for each of the multiple die that have a visual functional indicator;
powering up the wafer to electrically activate the multiple die and initiate operation of the test circuitry;
performing predetermined tests with the test circuitry for the multiple die; and
outputting a test result to each visual functional indicator to visually indicate which die of the multiple die passed the predetermined tests and which die failed the predetermined tests.

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- A' Contd
- (25) (Newly Presented) The method of claim 24 further comprising:
physically locating each functional indicator within a scribe area of the wafer.
- (26) (Newly Presented) The method of claim 24 further comprising:
recording each visual functional indicator with either a camera or a high
resolution imager to form a data base that is used by a singulation
tool to singulate the multiple die and segregate the multiple die
based on each visual functional indicator.
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